

Figure 1

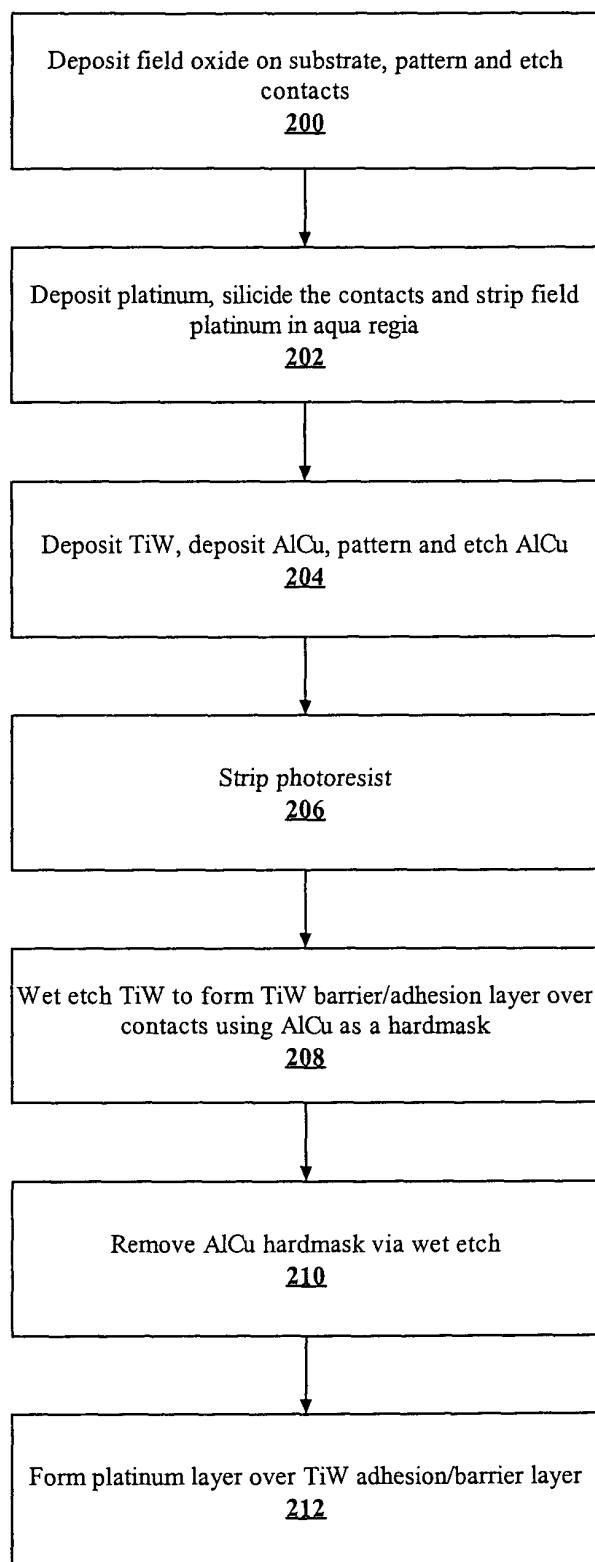


Figure 2

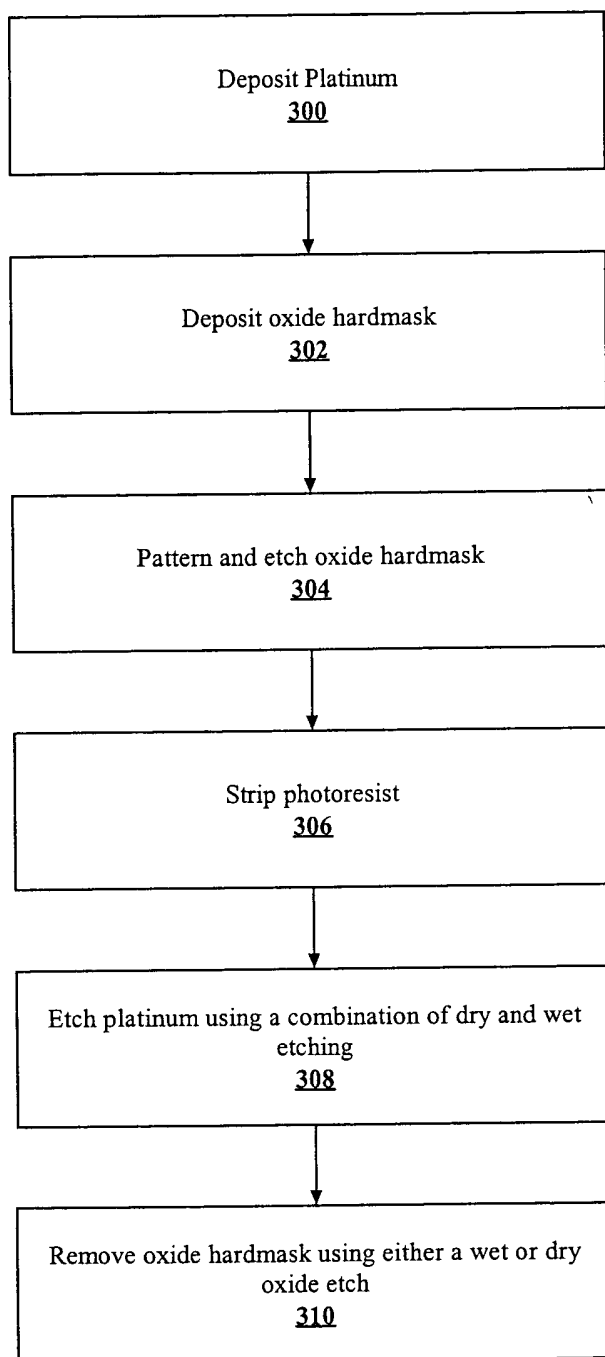


Figure 3

(1)

2011-01-01 10:00:00

- Pattern and etch contacts
- Strip resist
- Deposit Platinum and silicide the contacts
- Strip field Pt in aqua regia

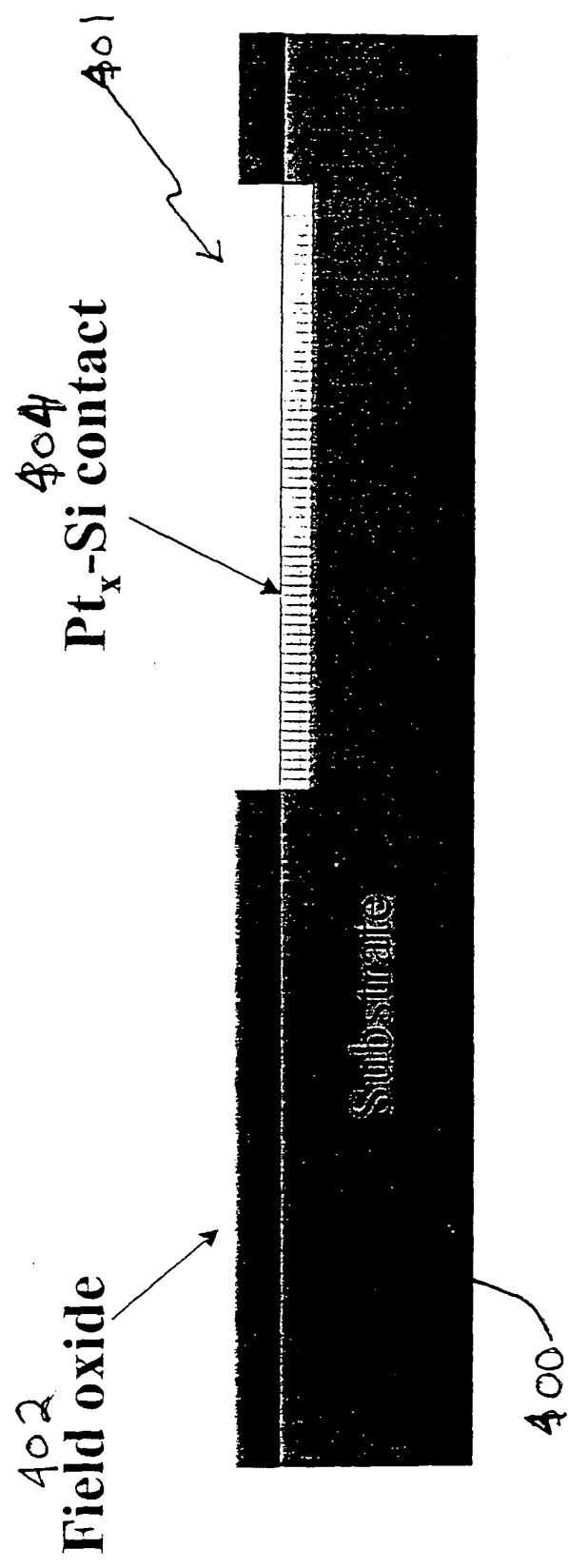


Figure 4a

Deposit TiW

Pattern and etch TiW barrier over contacts

Strip resist

406
TiW

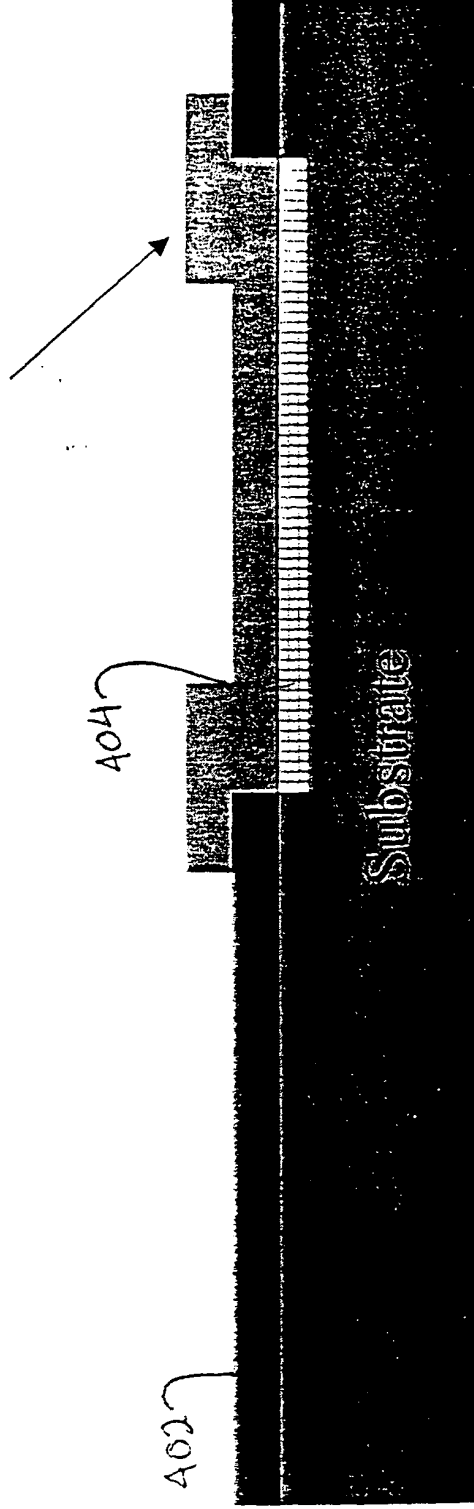


Figure 4b

Note: contingency field on reticle for TiW adhesion layer under all interconnect

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Deposit Platinum for interconnect

Deposit oxide for hardmask

Pattern and etch hardmask

Strip resist

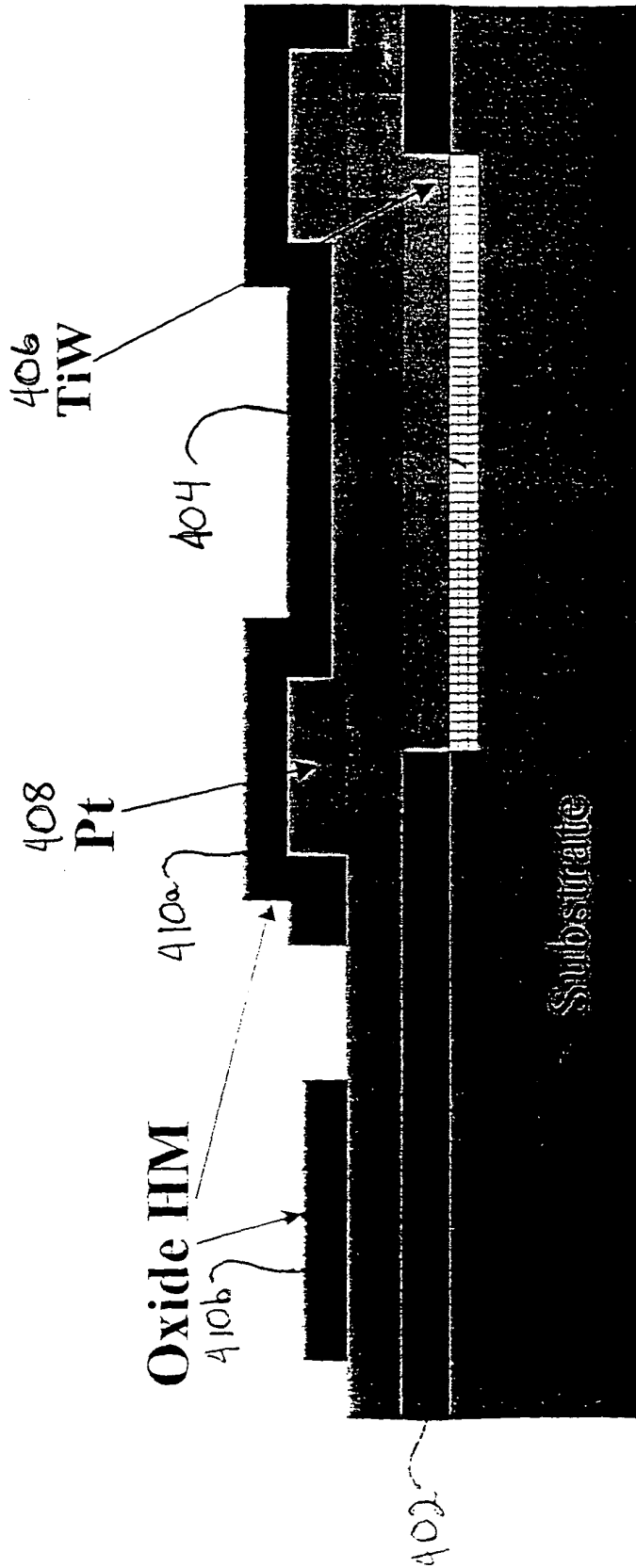


Figure 4c

Etch Platinum for interconnect

Remove hardmask

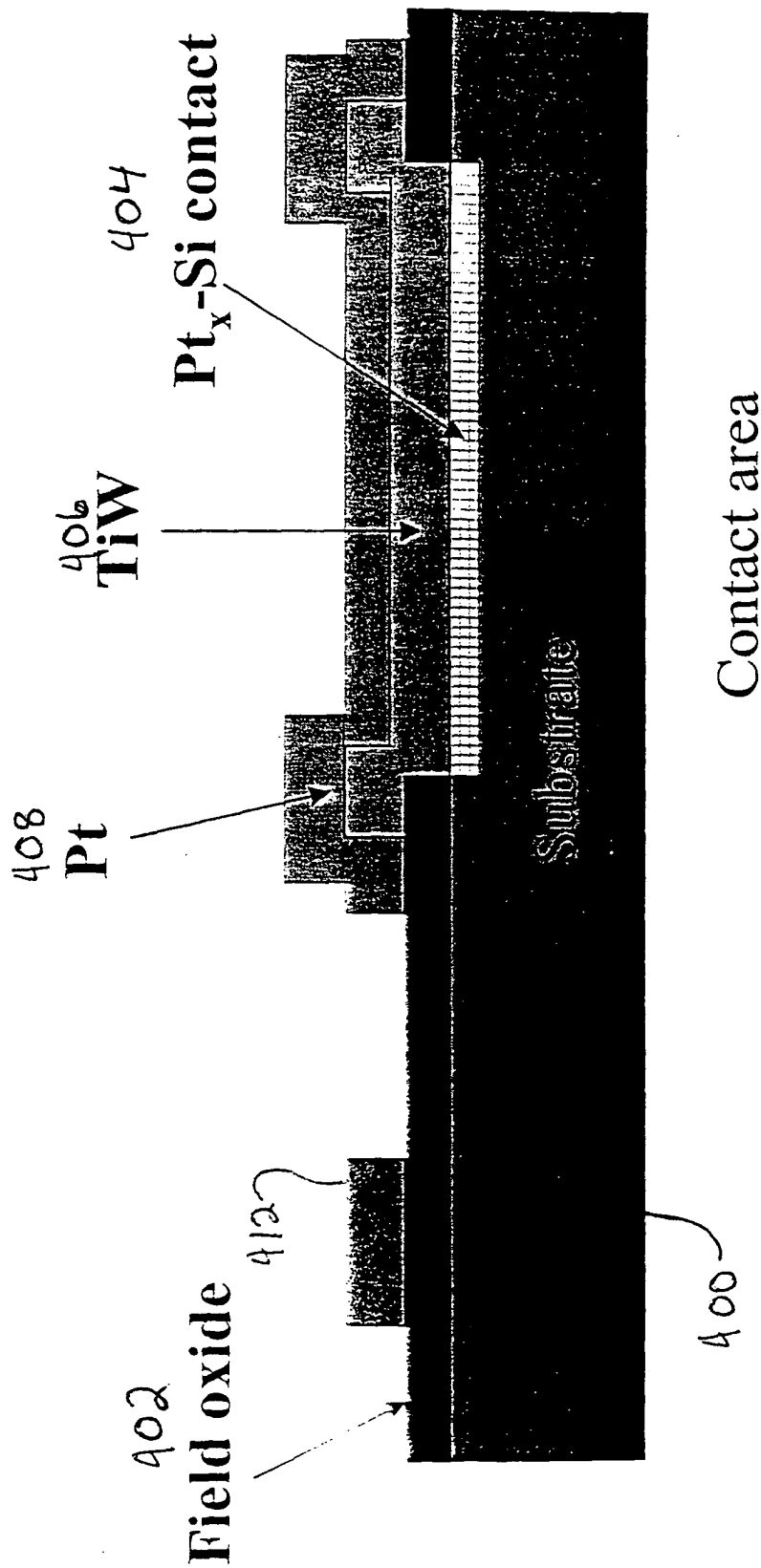


Figure 4d

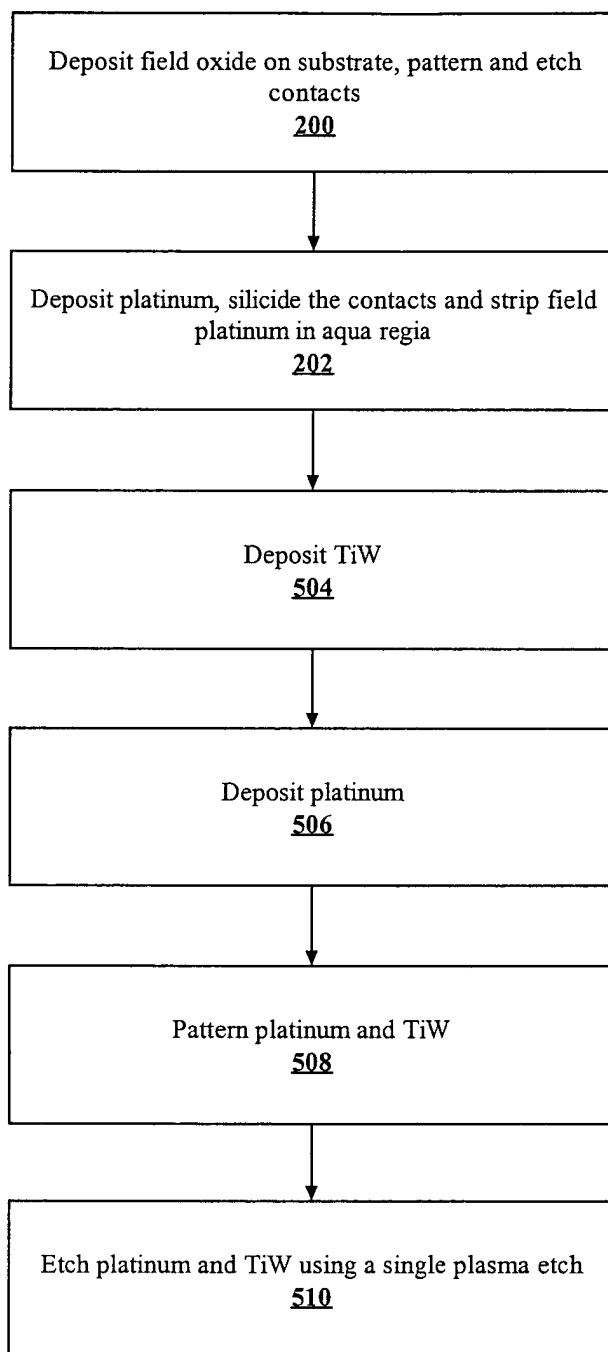


Figure 5

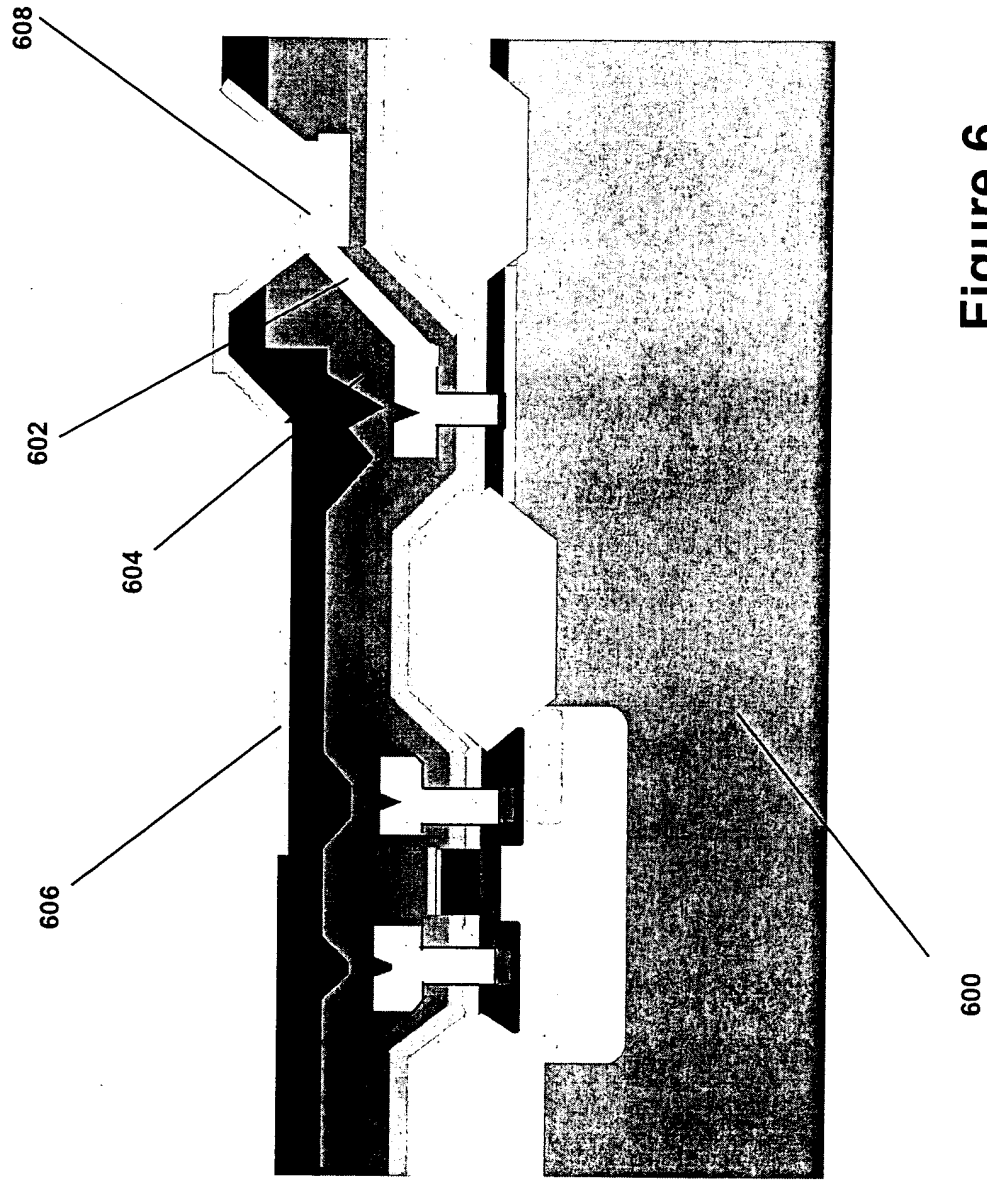


Figure 6